

Supplementary Data

CVD of Pure Copper Films From Novel Iso-Ureate complexes.

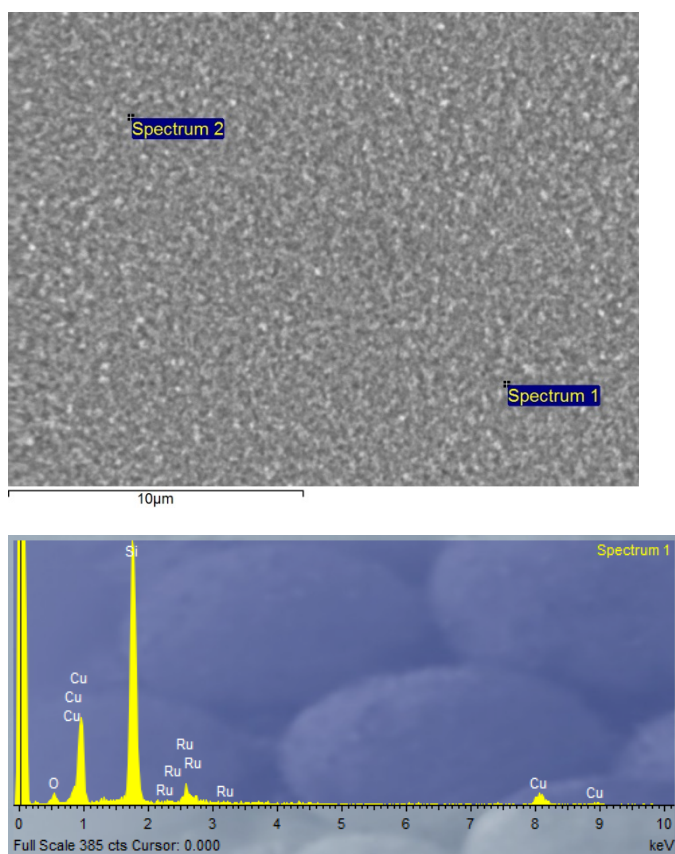
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Stephen P Richards[‡] and Andrew J. Kingsley[‡]

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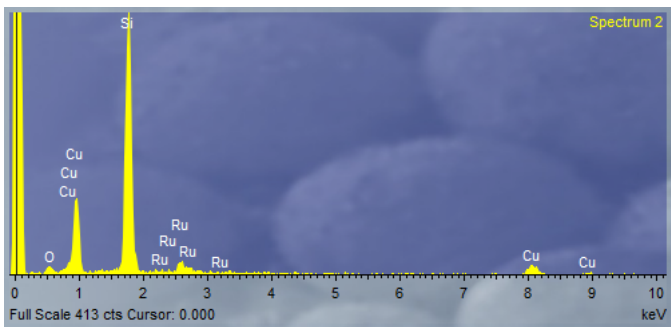
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E-mail: A.L.Johnson@bath.ac.uk

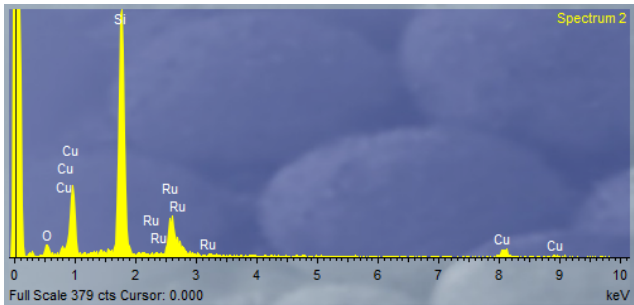
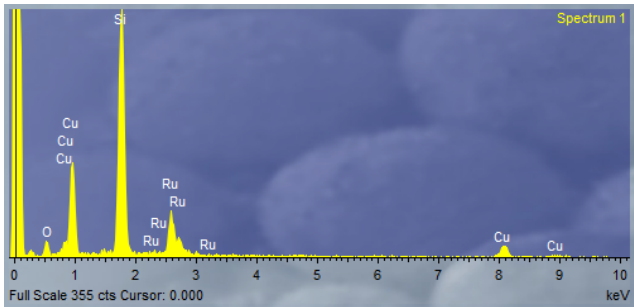
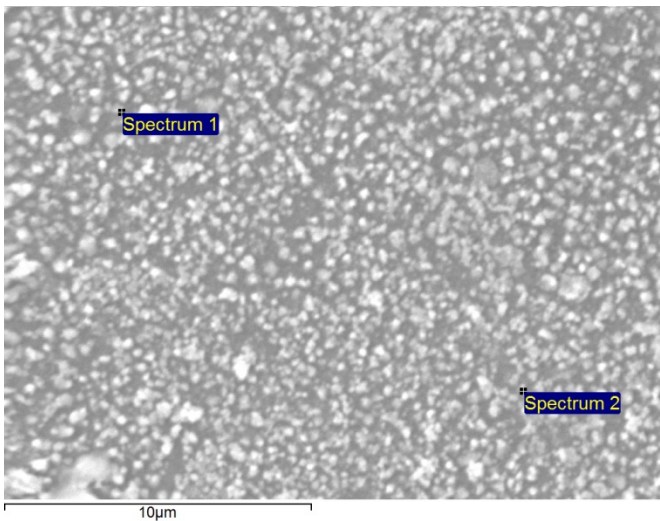
1) SEM image of Cu fim deposited at 250 °C and associated EDX spectra.



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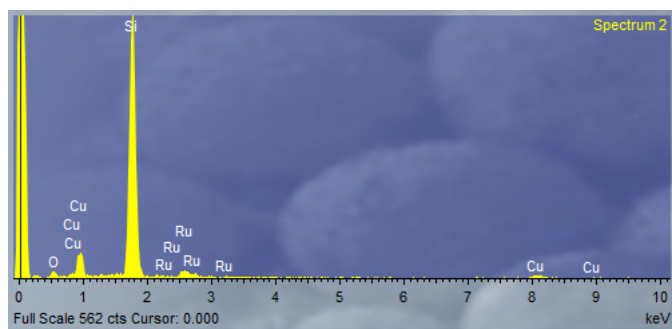
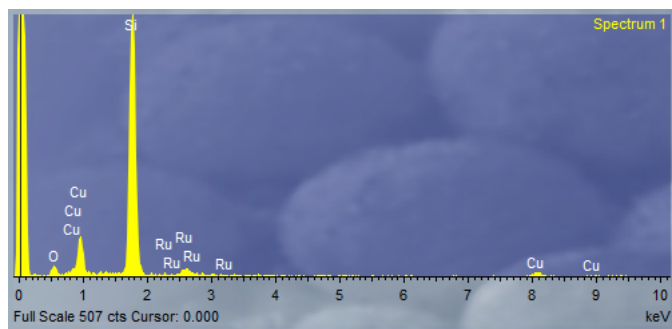
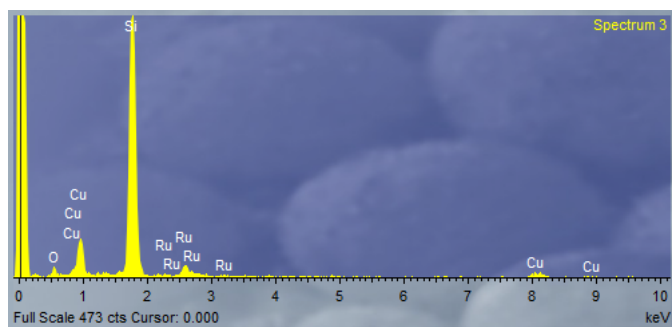
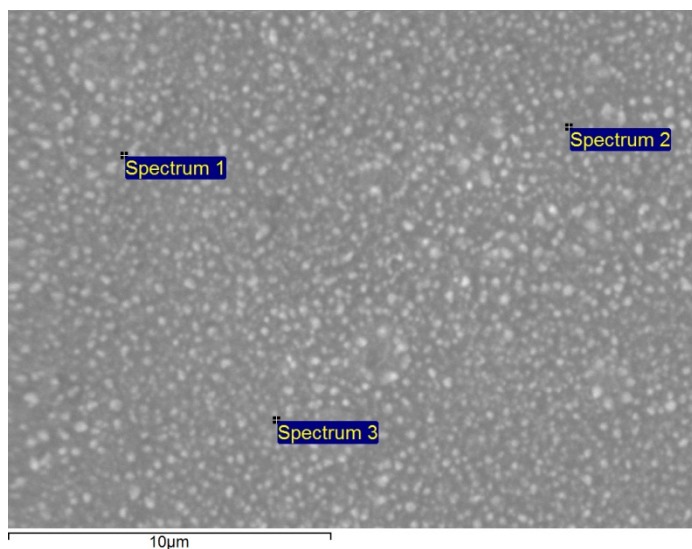


2) SEM image of Cu fim deposited at 300 °C and associated EDX spectra.



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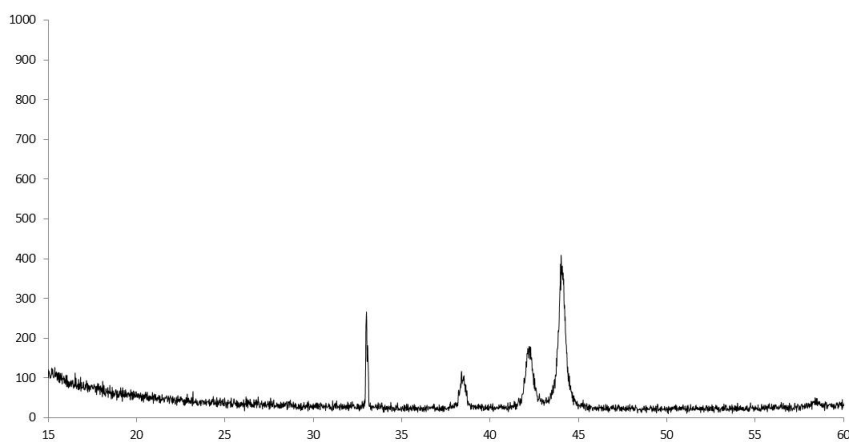
- 3) SEM image of Cu film deposited at 225 °C and subsequently annealed at 300 °C under H₂, and its associated EDX spectra.



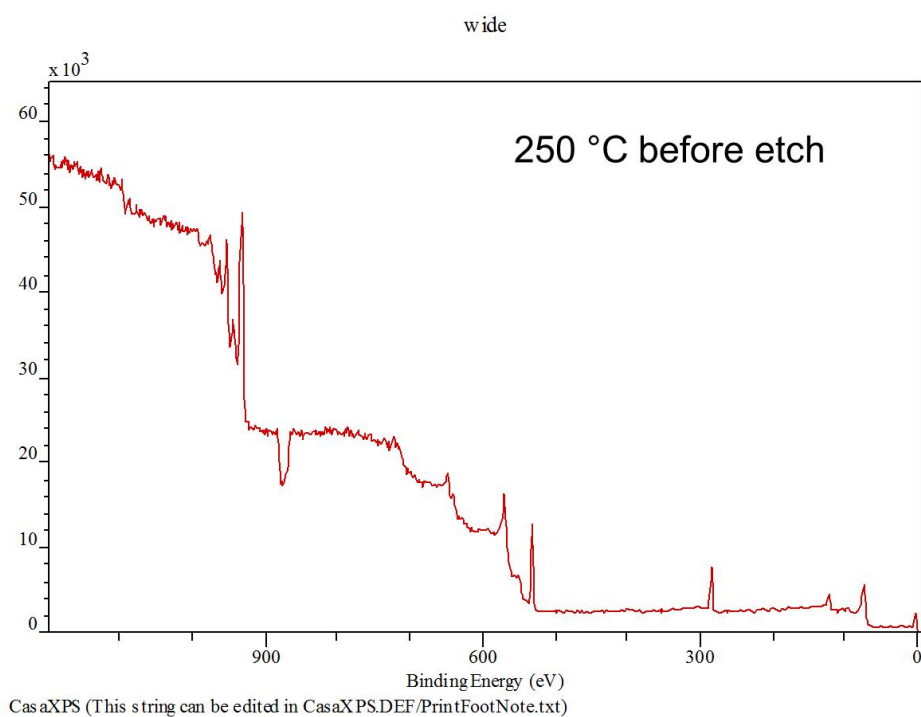
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- 4) PXRD spectrum of the Ru substrate used throughout the deposition experiments.

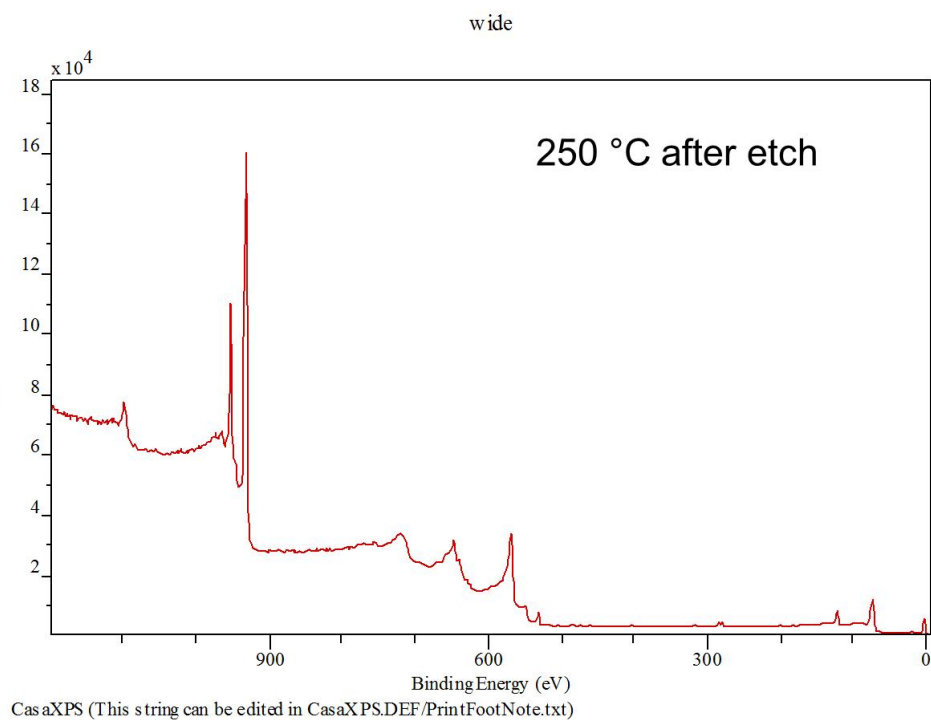
Si-Ru Substrate X-ray diffraction pattern



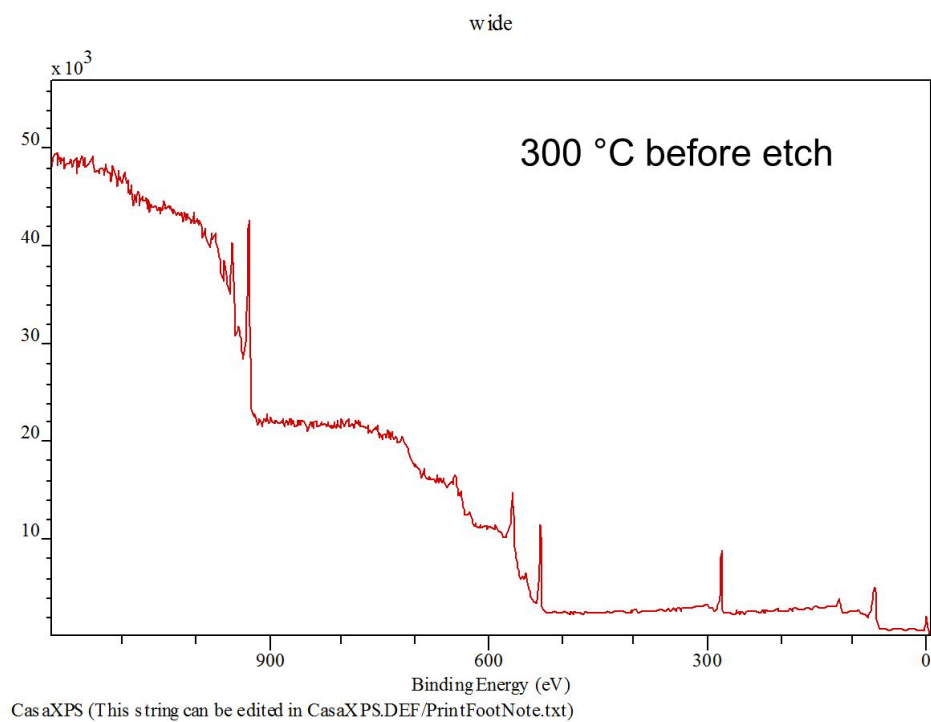
- 5) XPS spectra of the Cu films deposited at a substrate temperature of 250 °C (pre and post Ar-etching).



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- 6) XPS spectra of the Cu films deposited at a substrate temperature of 300 °C (pre and post Ar-etching).



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